

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S4	0	10/825910	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 14:53
S17 8	1	10/747036	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 15:02
S17 9	4	"6737750".pn. "5739581".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 15:08
S17 7	1190579	ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 15:08
S18 2	1741281	(( (printed adj circuit PC wiring ) adj (board card module ) pcb PWB motherboard mother adj board carrier)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 15:16
S18 3	3	S180 and S181	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 15:24
S18 4	1741281	S175 with 2with S182	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 15:25
S18 8	1379	"advanced semiconductor".as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 16:06
S18 7	628	"Chung, Chih-Ming".in. "Chung, Chih".in. "Chung, Ming".in. "Wang, Sung-Fei ".in. "Wang, Sung ".in. "Wang, Fei ".in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 16:06
S19 0	4403125	support\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 16:14

## EAST Search History

S18 9	36	S187 and S188	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 16:14
S19 1	6	S190 with S176 with S182 with S181	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 16:16
S18 6	14	S185 with S181	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 16:20
S19 4	7608436	ground reference power supply	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 16:21
S19 3	6674717	ground reference power	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 16:21
S19 2	27	S185 same S181	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 16:21
S18 1	4784228	ground reference	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 16:21
S19 5	30	S185 with S194	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 16:29
S19 7	2405473	(microchip micro adj chip chip integrated adj circuit die ic semiconductor adj (device element structure component module) )	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 16:30
S19 6	17	S183 S186	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 16:30

## EAST Search History

S13 5	2230578	(microchip micro adj chip chip integrated adj circuit die ic semiconductor adj (device element structure component module) )	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 16:30
S19 8	1684	S175 with S176 with S197	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 16:31
S18 5	301	S175 with S176 with S182	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 16:31
S19 9	214	S198 with S193	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 16:32
S20 0	103	S199 with S177	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 16:43
S20 3	1901325	better reliable	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 16:55
S20 2	1109	S176 with S201	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 16:55
S20 1	10926	solder near bond\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 16:55
S20 5	1742	S185 S198	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 16:56
S20 6	10	S205 same S202	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 16:57

## EAST Search History

S20 7	1772	S175 near9 S176	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 17:09
S20 4	6	S202 with S203	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 17:09
S20 9	2	"6011314".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 17:10
S20 8	9	S202 same S207	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 17:10
S21 0	19	S196 S180	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 17:46
S21 2	1	10/825910	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 17:47
S21 1	6	"6737750".pn. "5739581".pn. S178 10/825910	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 17:47
S18 0	5	"6737750".pn. "5739581".pn. S178	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/26 17:47
S21 6	664	(257/E23.102).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/27 09:25
S21 5	1557	(257/706).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/27 09:25

## EAST Search History

S21 4	6574	(257/706,686,707,777,796,E23.102).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/27 09:25
S21 3	20	S196 S211	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 09:25
S16 5	2643150	leg supporting arm	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 09:26
S17 5	467067	( heatsink ((heat thermal\$2) near (sink\$4 spread\$3 dissipat\$3 conducting conductive radiat\$4)) (cool\$3 near2 (device apparatus) ) )	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 09:35
S22 0	4008580	path conduct\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 10:04
S21 9	5465035	(heat\$4 thermal\$2 exotherm\$6 radiat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 10:04
S21 8	467428	( heatsink ((heat thermal\$2) near (sink\$4 spread\$3 dissipat\$3 conducting conductive radiat\$4)) (cool\$3 near2 (device apparatus) ) )	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 10:04
S22 1	232247	S219 near S220	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 10:06
S22 4	5740136	leg support\$4 arm column pillar	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 10:08
S22 2	24617	S218 near6 S217	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 10:08

## EAST Search History

S21 7	6159026	leg support\$4 arm column pillar elongat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 10:08
S22 5	21923	S218 near6 S224	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 10:28
S22 7	25493	S219 near S226	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 10:59
S22 6	1843401	path	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 10:59
S17 6	91871	(wir\$4 near bond\$4 wirebond\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 11:00
S22 8	91976	(wir\$4 near bond\$4 wirebond\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 11:01
S23 0	8	S229 same S228	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 15:07
L11	19	"6737750"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 15:07
L10	2	"6737750".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 15:07
S22 9	297	S225 same S227	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 16:27

## EAST Search History

L18	297	L15 same L17	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 16:27
L17	25493	L13 near L16	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 16:27
L16	1843401	path	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 16:27
L15	21923	L12 near6 L14	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 16:27
L14	5740136	leg support\$4 arm column pillar	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 16:27
L13	5465035	(heat\$4 thermal\$2 exotherm\$6 radiat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 16:27
L12	467428	( heatsink ((heat thermal\$2) near (sink\$4 spread\$3 dissipat\$3 conducting conductive radiat\$4)) (cool\$3 near2 (device apparatus) ) )	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 16:27
S22 3	9465	S221 same S222	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 16:31
L22	24617	L12 near6 L19	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 16:31
L21	232247	L13 near L20	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 16:31

## EAST Search History

L20	4008580	path conduct\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 16:31
L19	6159026	leg support\$4 arm column pillar elongat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 16:31
L25	3	23 same 24	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 16:50
L24	10693	ground adj wire	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 16:50
L23	9465	L21 same L22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 16:50
L26	6	22 same 24	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 16:54
L27	3	18 and 24	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/27 16:58